RS1AF THRU RS1MF

Surface Mount Fast Recovery Rectifiers Reverse Voltage - 50 to 1000 V Forward Current - 1 A

Features

- · Glass passivated chip juntion
- For surface mounted applications
- · Low profile package
- Fast reverse recovery time

Mechanical Data

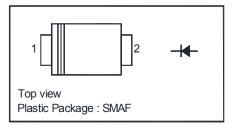
· Case: SMAF

• Terminals: Solder plated, solderable per

MIL-STD-750, Method 2026

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

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Parameter	Symbols	RS1AF	RS1BF	RS1DF	RS1GF	RS1JF	RS1KF	RS1MF	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	٧
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	٧
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	٧
Maximum Average Forward Rectified Current at T _C = 125°C	I _{F(AV)}	1						Α	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	30						А	
Maximum Forward Voltage at 1 A	V_{F}	1.3						V	
	I _R	5 50					μA		
Typical Junction Capacitance at $V_R = 4 \text{ V}$, $f = 1 \text{ MHz}$	C _j	Ç _j 15				pF			
Typical Thermal Resistance 1)	$R_{\theta JA}$	115					°C/W		
Maximum Reverse Recovery Time at $I_F = 0.5 \text{ A}$, $I_R = 1 \text{ A}$, $I_{rr} = 0.25 \text{ A}$			1	50		250	50	00	ns
Operating Junction and Storage Temperature Range	T_j , T_{stg}	- 55 to + 150						°C	

¹⁾ P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



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Electrical Characteristic Curves

Fig.1 Forward Current Derating Curve

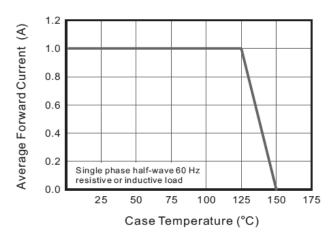


Fig.3 Typical Instaneous Forward Characteristics

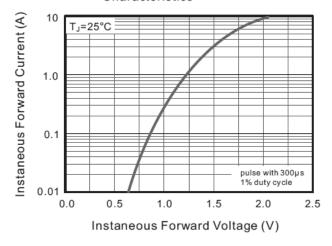


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

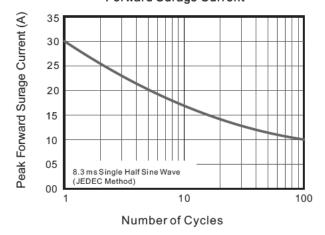


Fig.2 Typical Reverse Characteristics

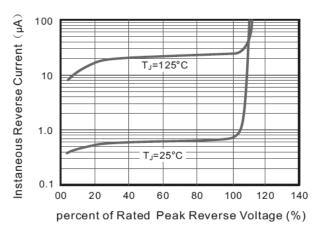
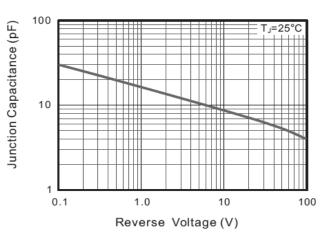


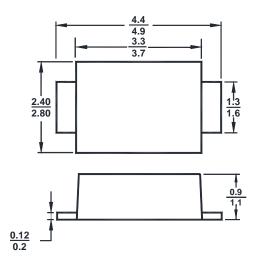
Fig.4 Typical Junction Capacitance



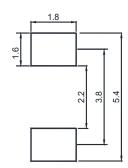


Package Outline Dimensions (Units: mm)

SMAF



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel	Size	D D 10 11 0 11	
Fackage		mm	inch	mm	inch	Per Reel Packing Quantity	
SMAF 12		4 ± 0.1	(0.157 ± 0.004)	178	7	3,000	
	12			330	13	10,000	

Marking information

" RS1* " = Part No.

Symbols	Marking	Symbols	Marking	Symbols	Marking	Symbols	Marking
RS1AF	RS1A	RS1BF	RS1B	RS1DF	RS1D	RS1GF	RS1G
RS1JF	RS1J	RS1KF	RS1K	RS1MF	RS1M		

[&]quot; III " = Cathode line

"Y" = Year

"W" = Week

Font type: Arial





[&]quot;YYWW" = Date Code Marking